

# GLF1220H, GLF1221H Nano Current Leakage I<sub>Q</sub>Smart<sup>™</sup> Load Switch with Slew Rate Control and Reverse Current Blocking

**Product Specification** 

# DESCRIPTION

The GLF1220H / GLF1221H is an advanced technology fully integrated  $I_QSmart^{TM}$  load switch device with reverse current blocking (RCB) protection and slew rate control of the output voltage.

The GLF1220H / GLF1221H offers industry leading reverse current blocking (RCB) protection performance, featuring an ultra-low threshold voltage. The GLF1220H / GLF1221H minimizes reverse current flow in the event that the VOUT voltage exceeds the VIN voltage.

The GLF1220H / GLF1221H load switch device supports an industry leading wide input voltage range that helps to improve system operating life and overall performance. One GLF120x device can be used in multiple voltage rail applications which helps mitigate inventory management and reduces BOM cost.

# FEATURES

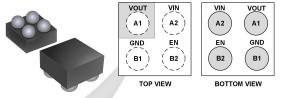
- Wide Input Range, V<sub>IN</sub>: 1.5 V to 5.5 V 6 V<sub>ABS</sub> Max
- I<sub>OUT</sub> Max: 1 A
- Low  $R_{ON}$ : 52 m $\Omega$  Typ. at 5.5  $V_{IN}$
- Ultra-Low I<sub>Q</sub>: 500 nA Typ at 5.5 V<sub>IN</sub>
- Ultra-Low I<sub>SD</sub>: 10 nA Typ at 5.5 V<sub>IN</sub>
- Reverse Current Blocking Protection
- Integrated Output Discharge Switch, GLF1221H
- Internal Pull-Down Resistor on EN Pin

# INTEGRATED POWER

# **APPLICATIONS**

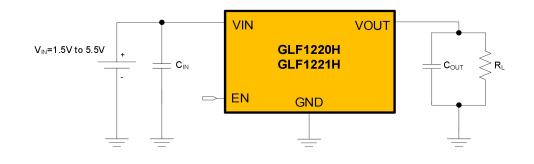
- Smart IoT Devices
- Portable Industrial Devices
- Low Power Subsystems
- Wearable Devices





0.67 mm x 0.67 mm x 0.425 mm 0.35 mm Pitch WL-CSP

# **APPLICATION DIAGRAM**





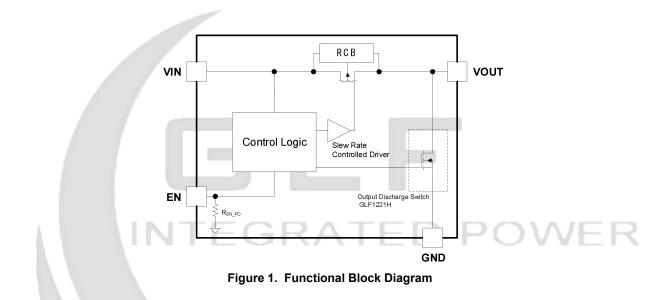
# GLF1220H, GLF1221H

# Nano Current Leakage I<sub>Q</sub>Smart<sup>™</sup> Load Switch with RCB

# ALTERNATE DEVICE OPTIONS

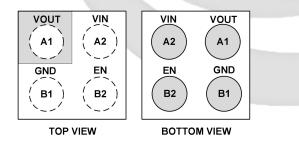
Part Number	Top Mark	R <sub>on</sub> (Typ) at V <sub>IN(MAX)</sub>	Reverse Current Blocking	Vout Rise Time at 3.3 V <sub>IN</sub>	Output Discharge	EN Activity
GLF1220H	Z	50 mQ	Vee	200 на	NA	Lliab
GLF1221H	R	R 52 mΩ Yes		390 µs	85 Ω	High

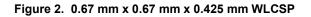
# FUNCTIONAL BLOCK DIAGRAM



# **PIN CONFIGURATION**

# **PIN DEFINITION**





Pin #	Name	Description
A1	VOUT	Switch Output
A2	VIN	Switch Input. Supply Voltage for IC
B1	GND	Ground
B2	EN	Enable to control the switch. The EN pin has an internal pull-down resistor.



### **ABSOLUTE MAXIMUM RATINGS**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions; extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Ра	Min.	Max.	Unit	
$V_{\text{IN}}, V_{\text{OUT}}, V_{\text{EN}}$	Each Pin Voltage Range to GND	- 0.3	6	V	
	Maximum Continuous Switch Current		1	^	
I <sub>OUT</sub>	Pulse, 300 us pulse and 2 % duty cycle		2	A	
PD	Power Dissipation at $T_A = 25 \degree C$		1	W	
T <sub>STG</sub>	Storage Junction Temperature	- 65	150	°C	
TA	Operating Temperature Range	- 40	85	°C	
θ <sub>JA</sub>	Thermal Resistance, Junction to Ambient (board dependent)			125	°C/W
<b>F</b> 8 <b>D</b>	Electrostatia Discharge Canability	Human Body Model, JESD22-A114	± 3		
ESD	Electrostatic Discharge Capability Charged Device Model, JESD22-C101				kV

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min.	Max.	Unit
V <sub>IN</sub>	Supply Voltage	1.5	5.5	V
TA	Ambient Operating Temperature	- 40	+ 85	°C

INTEGRATED POWER

# GLF1220H, GLF1221H

# Nano Current Leakage I₀Smart<sup>™</sup> Load Switch with RCB

# **ELECTRICAL CHARACTERISTICS**

Values are at  $V_{IN}$  = 3.3 V and  $T_A$  = 25 °C unless otherwise noted.

Symbol	Parameter	Conditio	ns	Min.	Тур.	Max.	Unit		
Basic Ope	eration	l			1				
V <sub>IN</sub>	Supply Voltage			1.5		5.5	V		
. (1)		V <sub>IN</sub> = 5.5 V, V <sub>EN</sub> = 0 V, I <sub>OUT</sub> = 0 n	nA		500	680			
lq <sup>(1)</sup>	Quiescent Current	V <sub>IN</sub> = 5.5 V, V <sub>EN</sub> = 0 V, I <sub>OUT</sub> = 0 n	nA, T <sub>A</sub> = 85 °C <sup>(4)</sup>		550				
		EN = Disable, I <sub>OUT</sub> = 0 mA, V <sub>IN</sub> = 1.5 V			1				
		EN = Disable, IOUT= 0 mA, VIN=	EN = Disable, I <sub>OUT</sub> = 0 mA, V <sub>IN</sub> = 2.5 V						
		EN = Disable, I <sub>OUT</sub> = 0 mA, V <sub>IN</sub> =	3.3 V		3		nA		
I <sub>SD</sub>	Shutdown Current	EN = Disable, I <sub>OUT</sub> = 0 mA, V <sub>IN</sub> =	4.5 V		4				
		EN = Disable, I <sub>OUT</sub> = 0 mA, V <sub>IN</sub> =	5.5 V		10	40			
		EN = Disable, I <sub>OUT</sub> = 0 mA, V <sub>IN</sub> =	5.5 V, T <sub>A</sub> = 55 °C <sup>(4)</sup>		50				
		EN = Disable, IOUT= 0 mA, VIN=	5.5V, T <sub>A</sub> = 85 °C <sup>(4)</sup>		275				
			T <sub>A</sub> = 25 °C		52	60			
		V <sub>IN</sub> = 5.5 V, I <sub>OUT</sub> = 500 mA	T <sub>A</sub> = 85 °C <sup>(4)</sup>		60				
			T <sub>A</sub> = 25 °C		57	65			
	On-Resistance	V <sub>IN</sub> = 4.5 V, I <sub>OUT</sub> = 500 mA	T <sub>A</sub> = 85 °C <sup>(4)</sup>		67				
Ron		V <sub>IN</sub> = 3.3 V, I <sub>OUT</sub> = 500 mA	T <sub>A</sub> = 25 °C		67	77	mΩ		
			T <sub>A</sub> = 85 °C <sup>(4)</sup>		79				
		V <sub>IN</sub> = 2.5 V, I <sub>OUT</sub> = 300 mA	T <sub>A</sub> = 25 °C		82		2		
		V <sub>IN</sub> = 1.8 V, I <sub>OUT</sub> = 300 mA	T <sub>A</sub> = 25 °C	DV	112	R			
		V <sub>IN</sub> = 1.5 V, I <sub>OUT</sub> = 100 mA	T <sub>A</sub> = 25 °C		142				
R <sub>DSC</sub>	Output Discharge Resistance	V <sub>EN</sub> = Low , I <sub>FORCE</sub> = 10 mA, GLF	1221H Only		85		Ω		
VIH	EN Input Logic High Voltage	V <sub>IN</sub> = 1.5 V to 5.5 V		1.2			V		
VIL	EN Input Logic Low Votlage	V <sub>IN</sub> = 1.5 V to 5.5 V				0.3	V		
Ren	EN Internal resistance	Internal Pull-down Resistance			10		MΩ		
I <sub>EN</sub>	EN Current (2)	V <sub>EN</sub> = 5.5 V			0.55	0.8	μA		
V <sub>RCB_TH</sub>	RCB Protection Threshold	Vout – Vin			40				
V <sub>RCB_RL</sub>	RCB Protection Release	V <sub>IN</sub> – V <sub>OUT</sub>			30		mV		
Switching	Characteristics <sup>(2)</sup>			•					
t <sub>dON</sub>	t <sub>dON</sub> Turn-On Delay				290				
t <sub>R</sub>	V <sub>OUT</sub> Rise Time	R <sub>L</sub> = 150 Ω, C <sub>OUT</sub> = 0.1 μF			390		1		
t <sub>dOFF</sub>	Turn-Off Delay <sup>(3), (4)</sup>	R <sub>L</sub> = 150 Ω, C <sub>OUT</sub> = 0.1 μF			16	1			
t⊧	V <sub>OUT</sub> Fall Time <sup>(3), (4)</sup>	GLF1220H			30	1	μs		
t <sub>dOFF</sub>	Turn-Off Delay <sup>(3), (4)</sup>	R∟= 150 Ω, Coυτ= 0.1 μF			16	1			
	V <sub>OUT</sub> Fall Time <sup>(3), (4)</sup>	GLF1221H			11	+	1		

Notes:

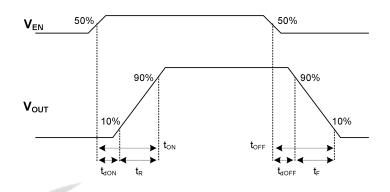
1. IQ does not include the enable pull down current (IEN) through the pull-down resistor REN.

2.  $t_{ON} = t_{dON} + t_R$ ,  $t_{OFF} = t_{dOFF} + t_F$ 

Output discharge path is enabled during off.
By design; characterized, not production tested.

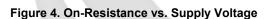


# TIMING DIAGRAM





#### 200 200 EN =V<sub>IN</sub> EN = V<sub>IN</sub> 180 180 160 160 ON RESISTANCE (mΩ) ON RESISTANCE (mΩ) VIN=1.5 140 140 120 120 85°C 100 100 25°C -40°C 80 80 =3.3' 60 60 40 40 V<sub>IN</sub>=5.5V 20 20 0 0 1.5 2.0 2.5 3.0 3.5 4.0 4.5 5.0 5.5 -40 -15 10 35 60 85 T<sub>J</sub>, JUNCTION TEMPERATURE (°C) SUPPLY VOLTAGE (V)



TYPICAL PERFORMANCE CHARACTERISTICS

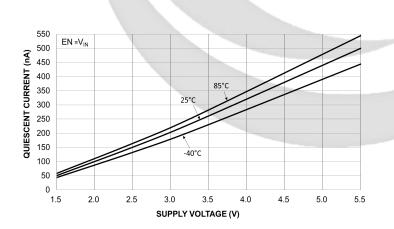
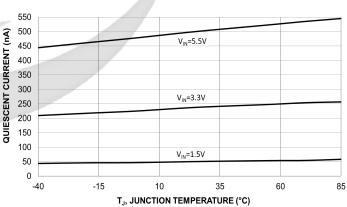
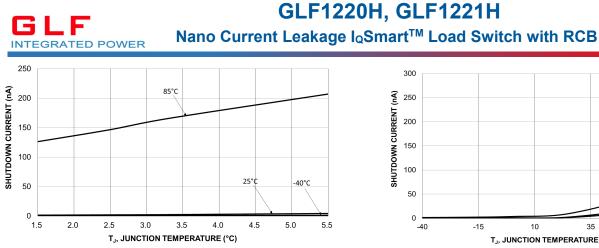


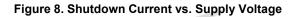
Figure 6. Quiescent Current vs. Supply Voltage

Figure 5. On-Resistance vs. Temperature









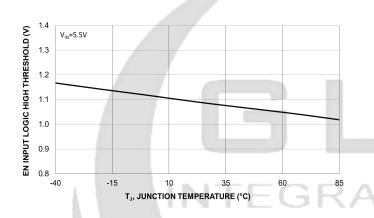


Figure 10. EN Input Logic High Threshold vs. Temperature

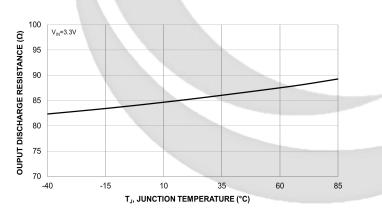


Figure 12. Output Discharge Resistance vs. Temperature **GLF1221H** 

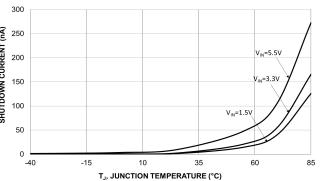


Figure 9. Shutdown Current vs. Temperature

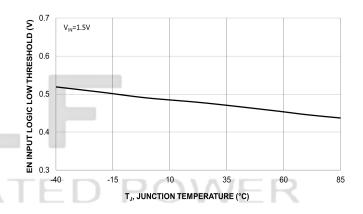


Figure 11. EN Input Logic Low Threshold vs. Temperature

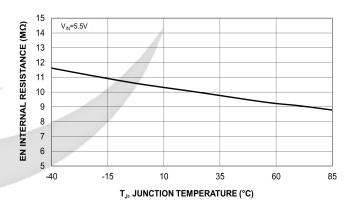


Figure 13. EN Internal Resistance vs. Temperature



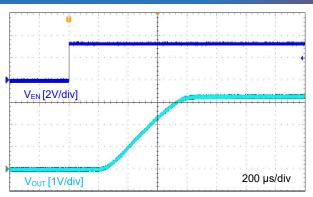


Figure 14. Turn-On Response, GLF1220H VIN=3.3 V, CIN=1.0  $\mu F,$  Cout=0.1  $\mu F,$  RL=150  $\Omega$ 

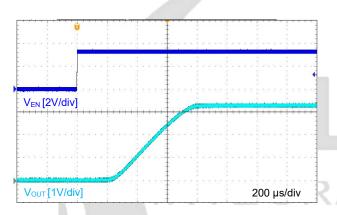
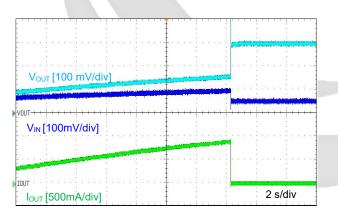
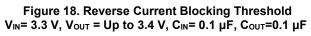


Figure 16. Turn-On Response, GLF1221H VIN=3.3 V, CIN=1.0  $\mu$ F, Cout=0.1  $\mu$ F, RL=150  $\Omega$ 





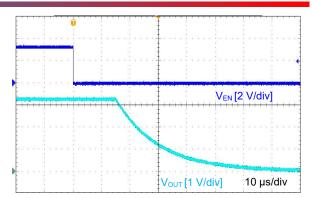


Figure 15. Turn-Off Response, GLF1220H V\_{IN}=3.3 V, C\_{IN}=1.0 \ \mu\text{F}, C\_{OUT}=0.1 \ \mu\text{F}, R\_L=150 \ \Omega

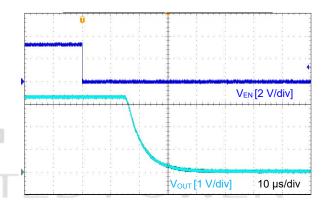


Figure 17. Turn-Off Response, GLF1221H VIN=3.3 V, CIN=1.0  $\mu F,$  Cout=0.1  $\mu F,$  RL=150  $\Omega$ 

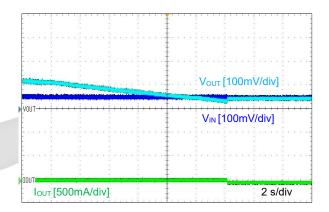


Figure 19. Reverse Current Blocking Release  $V_{\text{IN}}\text{=}3.3$  V,  $V_{\text{OUT}}\text{=}\text{Down to}3.2$  V,  $C_{\text{IN}}\text{=}0.1$   $\mu\text{F}$ ,  $C_{\text{OUT}}\text{=}0.1$   $\mu\text{F}$ 



# APPLICATION INFORMATION

The GLF1220H and GLF1221H are integrated 1 A, ultra-low  $I_QSmart^{TM}$  load switch devices with a fixed slew rate control to limit the inrush current during turn on. Each device is capable of operating over a wide input range from 1.5 V to 5.5 V with very low on-resistance to reduce conduction loss. In the off state, these devices consume very low leakage current to avoid unwanted standby current and save limited input power. The package is a 0.67 mm x 0.67 mm x 0.425 mm wafer level chip scale package, saving space in compact applications. It is constructed using 4 bumps, with a 0.35 mm pitch for manufacturability.

### Input Capacitor

The GLF1220H and GLF1221H do not require an input capacitor. However, to reduce the voltage drop on the input power rail caused by transient inrush current at start-up, a 0.1  $\mu$ F capacitor is recommended to be placed close to the VIN pin. A higher input capacitor value can be used to further attenuate the input voltage drop.

### **Output Capacitor**

The GLF1220H and GLF1221H do not require an output capacitor. However, use of an output capacitor is recommended to mitigate voltage undershoot on the output pin when the switch is turning off. Undershoot can be caused by parasitic inductance from board traces or intentional load inductances. If load inductances do exist, use of an output capacitor can improve output voltage stability and system reliability. The C<sub>OUT</sub> capacitor should be spaced close to the VOUT and GND pins.

### **EN Pin**

The GLF1220H and GLF1221H can be activated by forcing EN pin high level. Note that the EN pin has an internal pull-down resistor to help pull the main switch to a known "off state" when no EN signal is applied from an external controller.

### **Reverse Current Blocking**

The GLF1220H and GLF1221H have a built-in reverse current blocking protection which always monitors the output voltage level regardless of the status of EN pin to check if it is greater than the input voltage. When the output voltage goes beyond the input voltage by the reverse current blocking protection threshold voltage ( $V_{RCB_TH}$ ), the reverse current blocking function block turns off the switch. Note that some reverse current can occur until the  $V_{RCB_TH}$  is triggered. The main switch will resume normal operation when the output voltage drops below the input source by the reverse current blocking protection release voltage ( $V_{RCB_RL}$ ).

### **Output Discharge Function**

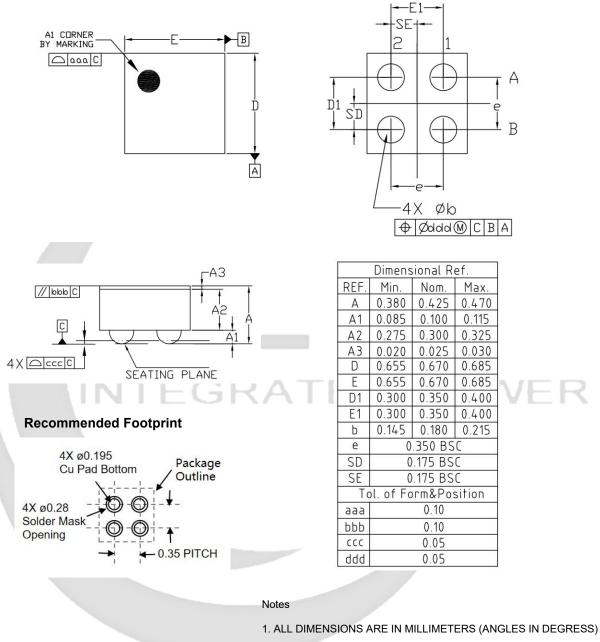
The GLF1221H has an internal discharge N-channel FET switch on the VOUT pin. When EN signal turns the main power FET to an off state, the N-channel switch turns on to discharge an output capacitor quickly.

### **Board Layout**

All traces should be as short as possible to minimize parasitic inductance effects. Wide traces for VIN, VOUT, and GND will help reduce signal degradation and parasitic effects during dynamic operation as well as improve the thermal performance at high load current.



# PACKAGE OUTLINE

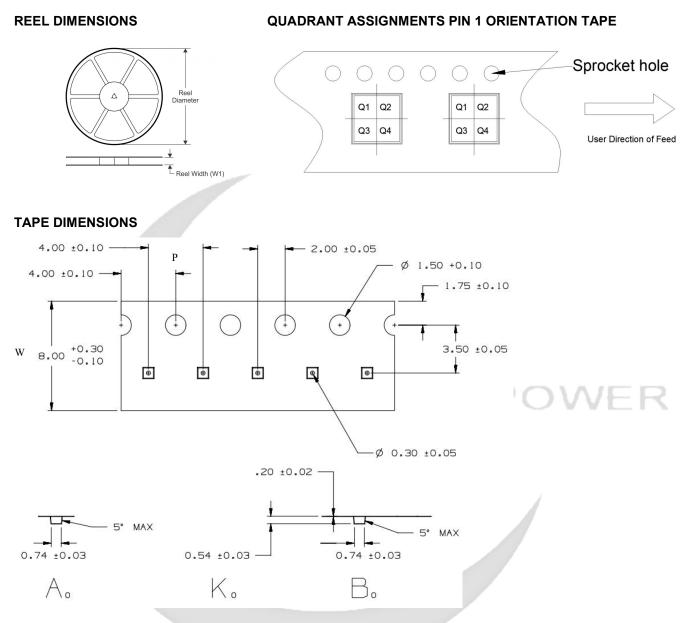


2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.

3. A3: BACKSIDE LAMINATION



# TAPE AND REEL INFORMATION



Device	Package	Pins	SPQ	Reel Diameter (mm)	Reel Width W1	A0	В0	К0	Р	w	Pin1
GLF1220H	WLCSP	4	4000	180	9	0.74	0.74	0.54	4	8	Q1
GLF1221H	WLCSP	4	4000	180	9	0.85	0.85	0.59	4	8	Q1

### Remark:

- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- C0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P1: Pitch between successive cavity centers



# GLF1220H, GLF1221H

# Nano Current Leakage l₀Smart<sup>™</sup> Load Switch with RCB

### **SPECIFICATION DEFINITIONS**

Document Type	Meaning	Product Status
Target Specification	This is a target specification intended to support exploration and discussion of critical needs for a proposed or target device. Parameters including the typical, minimum, and maximum values are desired, or target. GLF reserves the right to change contents at any time without warning or notification. A target specification will not guarantee the future production of the device.	Design / Development
Preliminary Specification	This is a draft version of a product specification which is under internal review and subject to change. GLF reserves the right to change the specification at any time without warning or notification. A preliminary specification will not guarantee the future production of the device.	Qualification
Product Specification	This document represents the characteristics of the device.	Production

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